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30A TRENCH SCHOTTKY RECTIFIER

Product Summary

SDT30B100D1

V _{RRM} (V)	I _O (A)	V _{F (MAX)} (V) @ +25°C	I _{R (MAX)} (μA) @ +25°C
100	30	0.85	120

Description and Applications

The SDT30B100D1 provides very low V_F and extremely excellent reverse leakage stability at high temperatures. It is ideal for use as a rectifier, freewheel diode or blocking diode in:

- DC-DC Converters
- AC-DC Adaptors

TO252 (DPAK) (Type TH)



Top View

Features and Benefits

- Low Forward Voltage Drop
- Excellent High Temperature Stability
- Soft, Fast Switching Capability
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: TO252 (DPAK) (Type TH)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Polarity: See Below
- Weight: 0.317 grams (Approximate)



Package Pin Out Configuration

Ordering Information (Note 4)

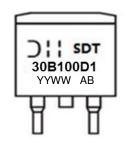
Part Number	Case	Packaging
SDT30B100D1-13	TO252 (DPAK) (Type TH)	2,500 pieces/reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

TO252 (DPAK) (Type TH)



Dil = Manufacturer's Code Marking SDT30B100D1 = Product Type Marking Code AB = Foundry and Assembly Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 17 = 2017) WW = Week (01 to 53)



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{RM}	100	V
Average Rectified Output Current	lo	30	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	130	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Case (Note 5)	$R_{ heta JC}$	2	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

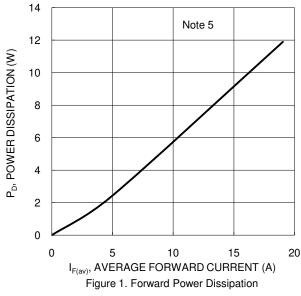
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

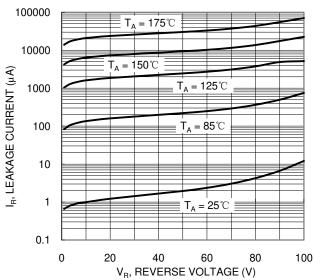
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	V _F		0.48 0.40 0.56 0.51 0.78 0.72	0.54 0.46 0.62 0.57 0.85 0.79	V	$\begin{split} I_F &= 5A, \ T_J = +25^{\circ}C \\ I_F &= 5A, \ T_J = +125^{\circ}C \\ I_F &= 10A, \ T_J = +25^{\circ}C \\ I_F &= 10A, \ T_J = +125^{\circ}C \\ I_F &= 30A, \ T_J = +25^{\circ}C \\ I_F &= 30A, \ T_J = +125^{\circ}C \\ \end{split}$
Leakage Current (Note 6)	I _R		12 5	120 20	μA mA	$V_R = 100V, T_J = +25$ °C $V_R = 100V, T_J = +125$ °C

Notes:

- 5. Test with 2inch*2inch Al board + 50mm*50mm*23mm Al heatsink.
- 6. Short duration pulse test used to minimize self-heating effect.







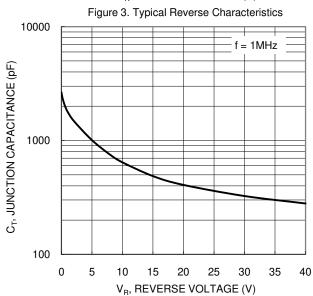


Figure 5. Typical Junction Capacitance

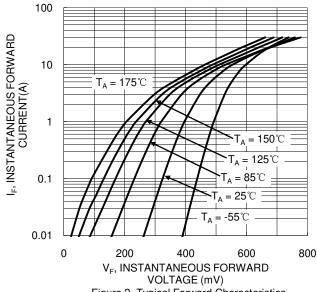


Figure 2. Typical Forward Characteristics

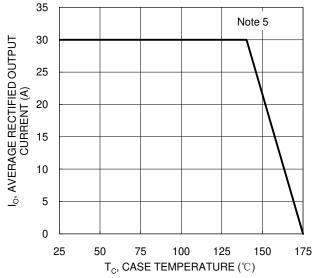


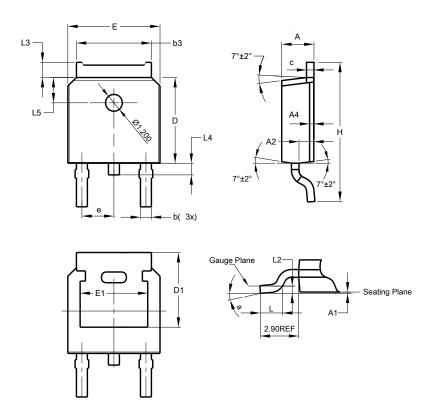
Figure 4. DC Forward Current Derating



Package Outline Dimensions

 $Please see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

TO252 (DPAK) (Type TH)

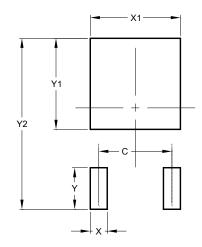


TO252 (DPAK) (Type TH)						
Dim	Min	Max	Тур			
Α	2.20	2.38	2.30			
A1	0.00	0.10	-			
A2	0.97	1.17	1.07			
A4	0.10 REF					
b	0.72	0.85	0.78			
b3	5.23	5.45	5.33			
C	0.47	0.58	0.53			
D	6.00 6.20 6.10					
D1	5.30 REF					
е	2.286 BSC					
Е	6.50	6.70	6.60			
E1	4.70	4.92	4.83			
Η	9.90	10.10	10.30			
L	1.40	1.70	1.60			
L2	0.51 BSC					
L3	0.90	1.25	-			
L4	0.60	1.00	0.80			
L5	1.70	1.90	1.80			
а	0°	8°	-			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK) (Type TH)



Dimensions	Value (in mm)	
С	4.572	
Х	1.060	
X1	5.632	
Υ	2.600	
Y1	5.700	
Y2	10.700	



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